



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-08-08
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	BKK7*MV03AAX	A	ZY1A	2017-08-08
Amount	UoM	Unit type	ST ECOPACK Grade	
130.25	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	8.6X3.9X1.52	16	gull wing	
Comment	Package: SO 14 .15 TO JEDEC MS-012 - MDF valid for CPs: L6564H and L6564HTR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	die backside metal	184

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BKK7*MV03AAX									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	Other inorganic materials	4.854	mg	supplier	die	Silicon (Si)	7440-21-3		4.692	mg	966625	36023				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.022	mg	4532	169				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.018	mg	3708	138				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.058	mg	11949	445				
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.003	mg	620	23				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1236	46				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.024	mg	4944	184				
				supplier	polymer die coating	PIXI Gamma-butyrolactone	96-48-0		0.031	mg	6386	238				
				Leadframe	Copper & its alloys	49.446	mg	supplier	alloy	Copper (Cu)	7440-50-8		47.461	mg	959855	364384
								supplier	alloy	Iron (Fe)	7439-89-6		1.169	mg	23642	8975
supplier	alloy	Zinc (Zn)	7440-66-6						0.065	mg	1315	499				
supplier	alloy	Iron Phosphide(FeP)	26508-33-8						0.020	mg	404	154				
supplier	metallization	Silver (Ag)	7440-22-4						0.731	mg	14784	5612				
supplier	glue	Resin A	9003-36-5						0.123	mg	70207	944				
Die Attach	Other Organic Materials	1.752	mg	supplier	glue	Resin B	68475-94-5		0.070	mg	39954	539				
				supplier	glue	Silver (Ag)	7440-22-4		1.349	mg	769977	10357				
				supplier	glue	Lactone	96-48-0		0.070	mg	39954	537				
				supplier	glue	Polyoxypropylenediamine	9046-10-0		0.070	mg	39954	537				
				supplier	glue	2,6-Diglycidyl phenyl allyl ether oligomer	Proprietary		0.070	mg	39954	537				
				supplier	wire	Gold (Au)	7440-57-5		0.240	mg	991736	1843				
Bonding wire	Other inorganic materials	0.242	mg	supplier	wire	Paladium (Pd)	7440-05-3		0.002	mg	8264	15				
				supplier	mold compound	Multi-aromatic Resin	Proprietary		5.368	mg	75002	41213				
				supplier	mold compound	Carbon Black	1333-86-4		0.358	mg	5002	2749				
Encapsulation	Other Organic Materials	71.571	mg	supplier	mold compound	Silica Fused	60676-86-0		61.551	mg	859999	472560				
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		1.431	mg	19994	10987				
				supplier	mold compound	Phenol Resin	25068-38-6		2.863	mg	40003	21981				
				supplier	connection coating	Tin (Sn)	7440-31-5		2.385	mg	1000000	18311				
Finishing	Other inorganic materials	2.385	mg	supplier	connection coating	Tin (Sn)	7440-31-5		2.385	mg	1000000	18311				